AMENDMENTS TO THE CLAIMS

This listing of claims will replace all prior versions and listings of claims in the application:

LISTING OF CLAIMS:

1. (original): A conductive particle,

which comprises a base particle and a conductive layer formed on a surface of said base particle,

said conductive layer having a non-crystal nickel plating layer in contact with the surface of said base particle and a crystal nickel plating layer, and

a proportion of a nickel crystal grain aggregate oriented in a nickel (111) plane derived from an integrated intensity ratio in X-ray diffraction measurement being 80% or more.

2. (original): The conductive particle according to claim 1,

wherein a phosphorus content of the non-crystal nickel plating layer is 10 to 18% and a phosphorus content of the crystal nickel plating layer is 1 to 8%.

3. (currently amended): The conductive particle according to claim 1~~ or 2~~,

wherein the conductive layer contains bismuth and/or thallium in an amount of 1000 ppm or less.

4. (currently amended): The conductive particle according to claim 1, ~~2 or 3,~~

wherein the conductive layer has a projection on the surface thereof.

5. (original): The conductive particle according to claim 4,

wherein the projection has a core material.

6. (original): The conductive particle according to claim 5,

wherein 80% or more of the core material is in contact with the base particle or is in a distance of 5 nm or less from said base particle.

7. (currently amended): The conductive particle according to claim 1, ~~2, 3, 4, 5 or 6,~~

wherein a gold layer is further formed on the surface of the conductive layer.

8. (currently amended): A method of producing the conductive particle according to claim 1, ~~2, 3, 4, 5, 6 or 7,~~ comprising:

a step 1 of providing a catalyst for the surface of the base particle;

a step 2 of using a nickel plating solution containing at least one complexing agent selected from the group consisting of citric acid, malic acid, succinic acid, propionic acid, lactic acid and acetic acid, and salts thereof and forming the non-crystal nickel plating layer on the surface of said base particle by adjusting a pH to 4.9 or less in a nickel plating reaction; and

a step 3 of using a nickel plating solution containing at least one complexing agent selected from the group consisting of citric acid, malic acid, succinic acid, propionic acid, lactic acid and acetic acid, and salts thereof and forming the crystal nickel plating layer by adjusting a pH to 7.2 to 9 in a nickel plating reaction.

9. (currently amended): An anisotropic conductive material,

which is obtained by dispersing the conductive particle according to claim 1, ~~2, 3, 4, 5, 6 or 7~~ in a resin binder.

10. (new): The conductive particle according to claim 2,

wherein the conductive layer contains bismuth and/or thallium in an amount of 1000 ppm or less.

11. (new): The conductive particle according to claim 2,

wherein the conductive layer has a projection on the surface thereof.

12. (new): The conductive particle according to claim 3,
wherein the conductive layer has a projection on the surface thereof.

13. (new): The conductive particle according to claim 2,
wherein a gold layer is further formed on the surface of the conductive layer.

14. (new): The conductive particle according to claim 3,
wherein a gold layer is further formed on the surface of the conductive layer.

15. (new): The conductive particle according to claim 4,
wherein a gold layer is further formed on the surface of the conductive layer.

16. (new): The conductive particle according to claim 5,
wherein a gold layer is further formed on the surface of the conductive layer.

17. (new): The conductive particle according to claim 6,
wherein a gold layer is further formed on the surface of the conductive layer.

18. (new): A method of producing the conductive particle according to claim 2, comprising:
a step 1 of providing a catalyst for the surface of the base particle;
a step 2 of using a nickel plating solution containing at least one complexing agent selected from the group consisting of citric acid, malic acid, succinic acid, propionic acid, lactic acid and acetic acid, and salts thereof and forming the non-crystal nickel plating layer on the surface of said base particle by adjusting a pH to 4.9 or less in a nickel plating reaction; and
a step 3 of using a nickel plating solution containing at least one complexing agent selected from the group consisting of citric acid, malic acid, succinic acid, propionic acid, lactic

acid and acetic acid, and salts thereof and forming the crystal nickel plating layer by adjusting a pH to 7.2 to 9 in a nickel plating reaction.

19. (new): A method of producing the conductive particle according to claim 3, comprising:

a step 1 of providing a catalyst for the surface of the base particle;

a step 2 of using a nickel plating solution containing at least one complexing agent selected from the group consisting of citric acid, malic acid, succinic acid, propionic acid, lactic acid and acetic acid, and salts thereof and forming the non-crystal nickel plating layer on the surface of said base particle by adjusting a pH to 4.9 or less in a nickel plating reaction; and

a step 3 of using a nickel plating solution containing at least one complexing agent selected from the group consisting of citric acid, malic acid, succinic acid, propionic acid, lactic acid and acetic acid, and salts thereof and forming the crystal nickel plating layer by adjusting a pH to 7.2 to 9 in a nickel plating reaction.

20. (new): A method of producing the conductive particle according to claim 4, comprising:

a step 1 of providing a catalyst for the surface of the base particle;

a step 2 of using a nickel plating solution containing at least one complexing agent selected from the group consisting of citric acid, malic acid, succinic acid, propionic acid, lactic acid and acetic acid, and salts thereof and forming the non-crystal nickel plating layer on the surface of said base particle by adjusting a pH to 4.9 or less in a nickel plating reaction; and

a step 3 of using a nickel plating solution containing at least one complexing agent selected from the group consisting of citric acid, malic acid, succinic acid, propionic acid, lactic acid and acetic acid, and salts thereof and forming the crystal nickel plating layer by adjusting a pH to 7.2 to 9 in a nickel plating reaction.